



Dept.: E/M

By: GJM:SNS:kmh

OSMM&N File No. 219891US-2 DIV

Serial No. NEW APPLICATION

In the matter of the Application of: HIDEAKI YOSHIDA ET AL
For: CONTACT PROBE AND PROBE DEVICE

The following has been received in the U.S. Patent Office on the date stamped hereon:

- ☒ 110 pp. Specification 20 Claims/Formal Drawings 84 Sheets (COPY)
and 8 pages Application Data Sheet
- ☒ Combined Declaration, Petition & Power of Attorney 5 pages (COPY)
 - ☐ List of Inventor Names and Addresses
- ☒ Utility Patent Application Transmittal ☐ CPA
- ☒ Notice of Priority ☐ Priority Doc
- ☒ Check for \$740.00 ☒ Dep. Acct. Order Form
- ☒ Fee Transmittal Form
 - ☐ Assignment/PTO 1595 pages:
 - ☐ Letter to Official Draftsman
 - ☐ Letter Requesting Approval of Drawing Changes
 - ☐ Formal Drawings sheets ☐ Formal
 - ☐ Letter
- ☒ Preliminary Amendment w/Marked-Up Copy
 - ☐ Information Disclosure Statement ☐ PTO-1449
 - ☐ Cited References
 - ☐ Search Report
 - ☐ Statement of Relevancy ☐ Cited Pending Applications
 - ☐ IDS/Related/List of Related Cases ☐ Election Response
 - ☐ Restriction Response
 - ☐ Rule 132 Declaration
 - ☐ Request for Extension of Time
 - ☐ Notice of Appeal
 - ☐ Brief
 - ☐ Issue Fee Transmittal
- ☒ White Advance Serial Number Card
 - ☐ Small Entity Status is Claimed
 - ☐
 - ☐



Due Date: February 19, 2002

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Declaration, Power Of Attorney and Petition

Page 1

WE (I) the undersigned inventor(s), hereby declare(s) that:

My residence, post office address and citizenship are as stated below next to my name,

We (I) believe that we are (I am) the original, first, and joint (sole) inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled

CONTACT PROBE AND PROBE DEVICE

the specification of which

☐ is attached hereto.

☒ was filed on May 23, 1997 as

Application Serial No. _____

and amended on _____.

☐ was filed as PCT international application

Number _____

on _____,

and was amended under PCT Article 19

on _____ (if applicable).

We (I) hereby state that we (I) have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

We (I) acknowledge the duty to disclose information known to be material to the patentability of this application as defined in Section 1.56 of Title 37 Code of Federal Regulations.

We (I) hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed. Prior Foreign Application(s)

Application No.	Country	Day/Month/Year	Priority Claimed
HEI 8-128570	JAPAN	05/23/96	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
HEI 8-259829	JAPAN	09/30/96	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
HEI 8-259831	JAPAN	09/30/96	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
HEI 8-303322	JAPAN	11/14/96	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
HEI 8-306829	JAPAN	11/18/96	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
HEI 8-324430	JAPAN	12/04/96	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
HEI 8-349119	JAPAN	12/26/96	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No

COT 1/96

We (I) hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below.

_____	_____
(Application Number)	(Filing Date)
_____	_____
(Application Number)	(Filing Date)

We (I) hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

Application Serial No.	Filing Date	Status (pending, patented, abandoned)
_____	_____	_____
_____	_____	_____
_____	_____	_____

And we (I) hereby appoint: Norman F. Oblon, Registration Number 24,618; Marvin J. Spivak, Registration Number 24,913; C. Irvin McClelland, Registration Number 21,124; Gregory J. Maier, Registration Number 25,599; Arthur I. Neustadt, Registration Number 24,854; Richard D. Kelly, Registration Number 27,757; James D. Hamilton, Registration Number 28,421; Eckhard H. Kuesters, Registration Number 28,870; Robert T. Pous, Registration Number 29,099; Charles L. Gholz, Registration Number 26,395; Vincent J. Sunderdick, Registration Number 29,004; William E. Beaumont, Registration Number 30,996; Steven B. Kelber, Registration Number 30,073; Robert F. Gnuse, Registration Number 27,295; Jean-Paul Lavalleye, Registration Number 31,451; Timothy R. Schwartz, Registration Number 32,171; Stephen G. Baxter, Registration Number 32,884; Martin M. Zoltick, Registration Number 35,745; Robert W. Hahl, Registration Number 33,893; Richard L. Treanor, Registration Number 36,379; Steven P. Weihrouch, Registration Number 32,829; John T. Goolkasian, Registration Number 26,142; Marc R. Labgold, Registration Number 34,651; William J. Healey, Registration Number 36,160; Richard L. Chinn, Registration Number 34,305; Steven E. Lipman, Registration Number 30,011; Carl E. Schlier, Registration Number 34,426; James J. Kulbaski, Registration Number 34,648; Catherine B. Richardson, Registration Number 39,007; Richard A. Neifeld, Registration Number 35,299; J. Derek Mason, Registration Number 35,270; and Jacques M. Dulin, Registration Number 24,067; our (my) attorneys, with full powers of substitution and revocation, to prosecute this application and to transact all business in the Patent Office connected therewith; and we (I) hereby request that all correspondence regarding this application be sent to the firm of OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C., whose Post Office Address is: Fourth Floor, 1755 Jefferson Davis Highway, Arlington, Virginia 22202.

We (I) declare that all statements made herein of our (my) own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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Signature: 

Karen L. Hudson

Total number of pages including this page: 4

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By: KLH/

OSMM&N File No. 219891US-2DIV

Serial No. 10/076,508

Patent No.

In the matter of: MITSUBISHI MATERIALS CORPORATION

For: Assignment of Application

☒ Dep. Acct. Order Form

☒ Assignment/PTO 1595 Pages: 3

Linked to OPTMS	
<u>2/13/04</u>	<u> </u>
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